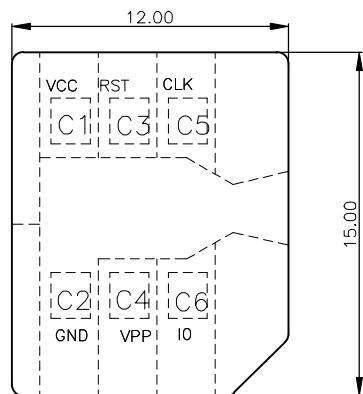
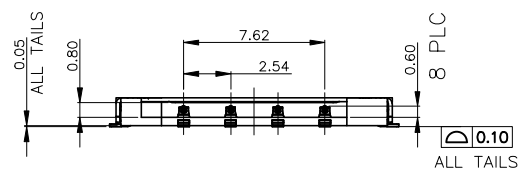
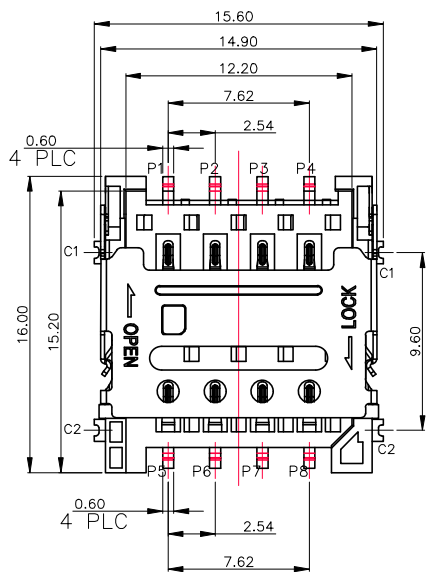




REV.	ECN NO OR DESCRIPTION	REVISED	DATE

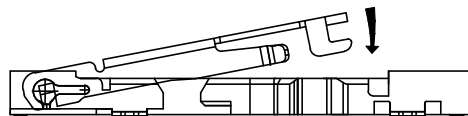
NOTES:

- 1) MATERIAL:
HOUSING: HI-TEMP. PLASIC UL 94V-0
CONTACT: COPPER ALLOY
SHELL: STAINLESS STEEL
- 2) FINISH:
CONTACT: GOLD FLASH PLATED ON CONTACT AREA;
GOLD FLASH PLATED ON SOLDER TAILS,

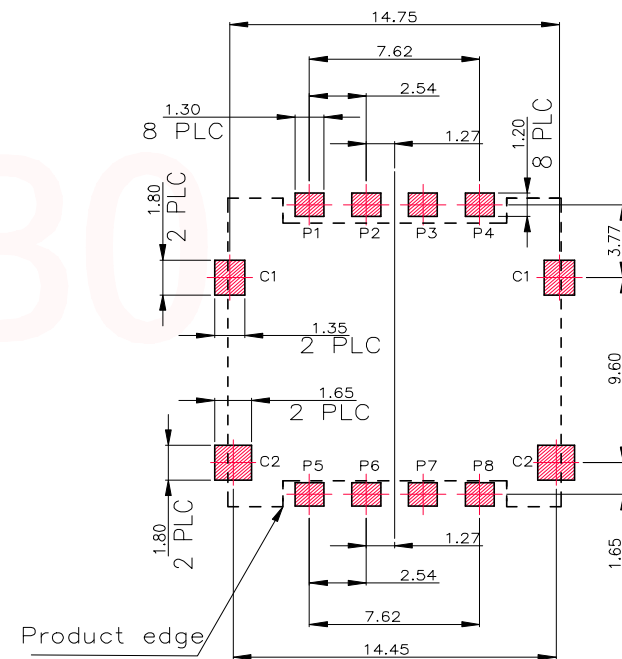
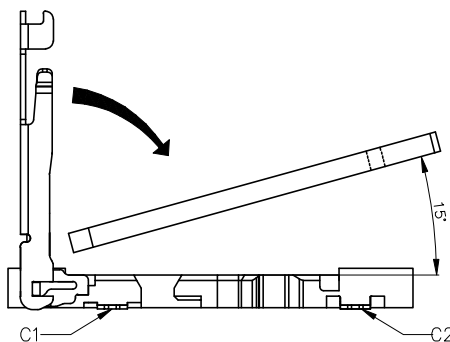
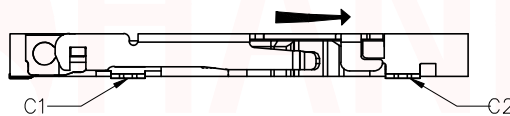


芯片面朝下视图

MICRO SIM CARD	
PIN NO.	DESCRIPTION
P1	VCC
P2	RST
P3	CLK
P4	RESERVED
P5	GND
P6	VPP
P7	I/O
P8	RESERVED



STEP II



RECOMMENDED PCB LAYOUT(TOP VIEW)
GENERAL TOLERANCES: ±0.05

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: ANGLES:
X : ±0.25 X : ±2°
X.X : ±0.15 X.X : ±1°
X.XX : ±0.10

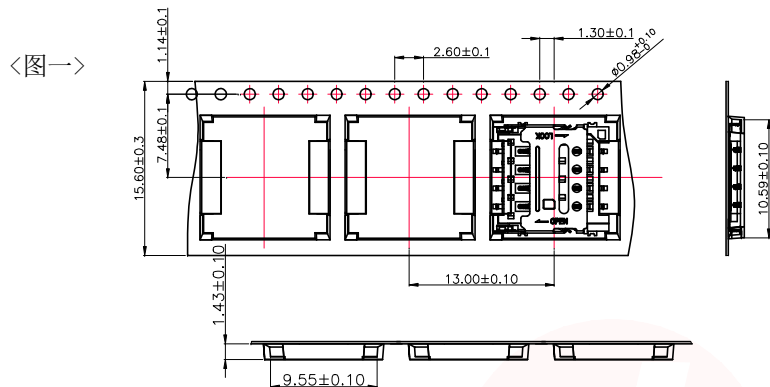


东莞市汉博电子科技有限公司
DONGGUAN HANBO TECHNOLOGY CO., LTD

TITLE	MICRO SIM CARD 8PIN 1.5H (掀盖式4×2PIN)			
DWN	xiong	PART NO.	SMO-1620	
CHKD	lee	SCALE:1:1	UNIT: mm	
APVD	wang	SIZE: A4	SHEET:1OF 1	REV: A4
CUSTOMER COPY				

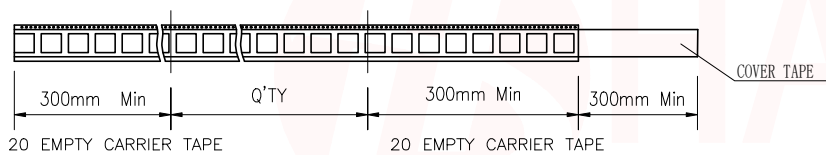


REV.	ECN NO OR DESCRIPTION	REVISED	DATE

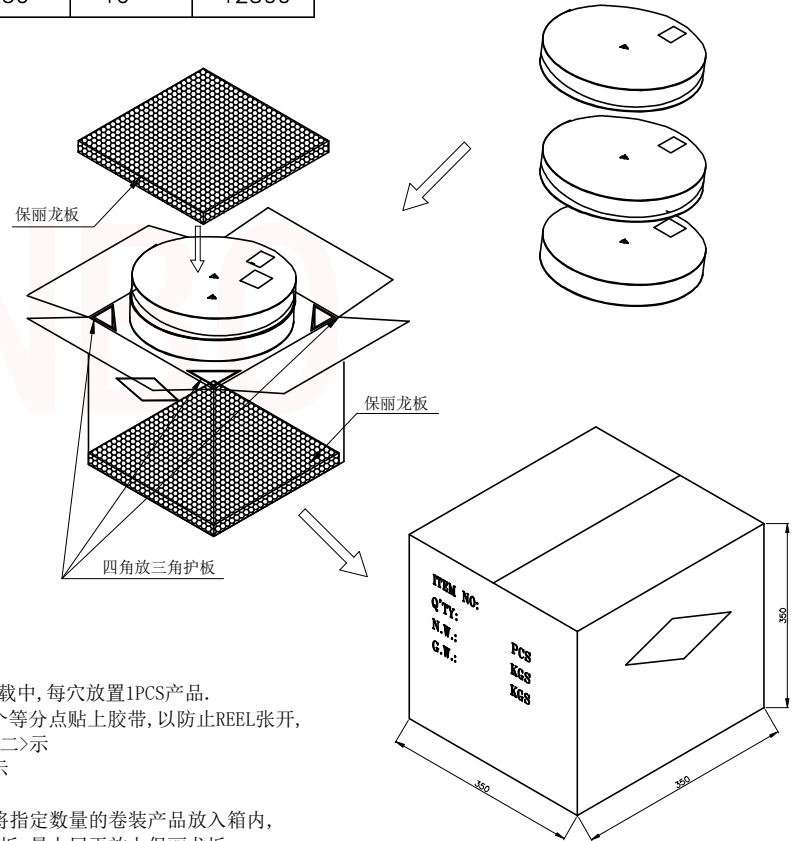


<TABLE 1> PACKAGING QUANTITY

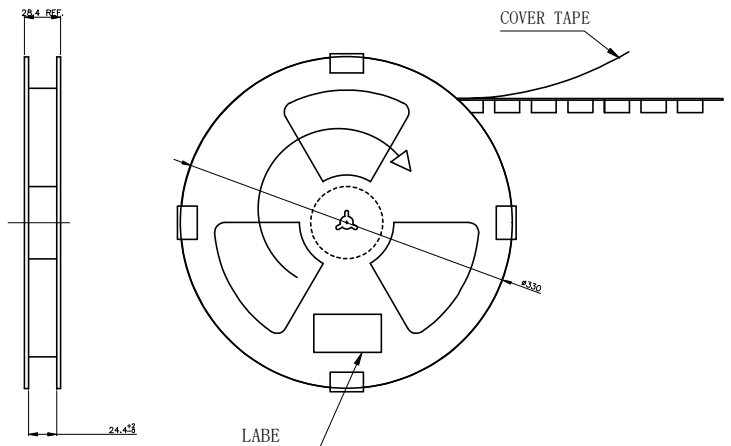
QTY/REEL	REEL/CARTON	QTY/CARTON
1250	10	12500



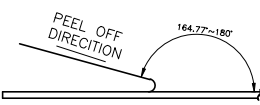
<图三>



<图二>



COVER TAPE PEELING FORCE: 50gf~150gf



NOTE:

- 依<图一>示放置产品于下载中, 每穴放置1PCS产品.
- 包装机包好后, 在REEL的个等分点贴上胶带, 以防止REEL张开, 每REEL贴1PCS标签, 如<图二>示
- 包装数量见如<TABLE 1>示
- 包装成箱见如<图三>示
箱底放保丽龙板, 再依次将指定数量的卷装产品放入箱内, 四角分别放入四个三角护板, 最上层再放上保丽龙板.
- 封箱, 在封好的纸箱上按客户要求写上料号, 数量等

UNLESS OTHERWISE SPECIFIED TOLERANCES		东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD		
DECIMALS:	ANGLES:	TITLE	MICRO SIM CARD 8PIN 1.5H (掀盖式4×2PIN)	
X :±0.25	X :±2°	DWN	xiong	PART NO. SMO-1620
X.X :±0.15	X.X :±1°	CHKD	lee	SCALE:1:1 UNIT: mm
X.XX :±0.10		APVD	wang	SIZE: A4 SHEET:10F 1 REV: A4
CUSTOMER COPY				